

WHAT IS CLAIMED IS:

1. An image sensor to be electrically connected to a printed circuit board,
comprising :

a substrate having an upper surface formed with a plurality of first
5 connected points projecting over the upper surface and a lower surface ;

a frame layer being arranged on the upper surface of the substrate so as to
form a cavity together with the substrate ;

a photosensitive chip being formed with a plurality of bonding pads and
being mounted on the upper surface of the substrate and within the cavity ;

10 a plurality of wires, each wire electrically connected the bonding pad of first
photosensitive chip to the first connected point of the substrate : and

a transparent layer covered on the frame layer for covering the
photosensitive chip so that the photosensitive chip may receive optical signals
passing through the transparent layer respectively, at the periphery of the
15 transparent layer formed with cut -corner.

2. The image sensor according to claim 1, wherein the lower surface of the
substrate has a plurality of second connected points for connecting the printed
circuit board.

3. The image sensor according to claim 1, wherein the transparent layer is a
20 piece of transparent glass.

4. The image sensor according to claim 1, wherein the cut-corner of the transparent layer is a spherical-shaped.

5. The image sensor according to claim 1, wherein the cut-corner of the transparent layer is an incline-shaped.